LEB 1.			
As a below named inventor	Landschy declare that:		
My residence, post office a	nd citizenship are as stated below next to n	ıy name,	
names are listed below) of	first and sole inventor (if only one name in the subject matter claimed and for which MOBILE COMMUNICATION SYSTEM	a patent is sought on the inve	erst and joint inventor (if plural ention cutitled METHOD FOR
[X] is attached hereto [an] was filed on as a	Application Serial No(if applicable)	and was
I hereby state that I have amended by any amendmen	reviewed and understand the contents of a referred to above.	the above identified specification	ation, including the claims, as
I acknowledge the duty to Code of Federal Regulation	disclose information which is known to make the section 1.56(a).	e to be material to patentabilit	y in accordance with Title 37,
certificate, or 365(a) of an America, listed below and l	rity benefits under 35 U.S.C. 119(a)-(d) or y PCT international application which desired also identified below, by checking the application having a filing date before that	signated at least one country or box, any foreign application for	ther than the United States of
Prior Forcign Application <u>Number</u>	(s): <u>Country</u>	Foreign Fîli: <u>Month/Day</u>	
71969/2000	Republic of Korea	11/30)/2000
hereby claim the benefit un Application Number(s):	nder 35 U.S.C.119(e) of any United States _j <u>Filing Date(Mo</u>	provisional application(s) listed nth/Day/Year)	below.
hereby claim the benefit unesignating the United State	nder 35, U. S. C. 120 of any United States as of America, listed below and, insofar as	application(s), or 365(c) of any	PCT international application
of disclosed in the prior Un 12, I acknowledge the dut	ited States or PCT international application y to disclose information which is material date of the prior application and the national	n in the manner provided by the	first paragraph of 35 U. S. C. 37 CFR 1.56 which became
rior U.S. Application r PCT Parent Number	Filing Date(Month/Day/	Year) Parent Pa	tent Number (if applicable)
		-	
hereby declare that all state clief are believed to be true	ements made herein of my own knowledge; and further that these statements were m	ge are true and that all statementate with the knowledge that w	nts made on information and

I like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

I hereby appoint the following attorney(s) and/or agent(s):Daniel Y.J. Kim, Registration No. 36,186 and Mark L. Fleshner, Registration No. 34,596; Carl R. Wesolowski, Registration No. 40,372, John C. Eisenhart, Registration No. 38,128, Rene A. Vasquez, Registration No. 38,647; Stuart I. Smith, Registration No. 42,159; Carol L. Druzbick, Registration No. 40,287; Anthony H.Nourse, Registration No. 46,121; and Margaret A. Burke, Registration No. 34,474, all of

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with full power of substitution and revocation, to prosecute this application and to transact all be Office connected therewith, and all future correspondence should be addressed to them.	usiness in	the Patent and Trademark
	*******	************
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Inventor's signature:	Date:	Nov. 29, 2001
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Full name of joint inventor(s):		
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Residence:		
Citizenship:		
Post Office Address:		
dooqqqtxxxxxxxxoooqqqxxxxxxooqqqxxxxxxxooqqqxxxxxx	*******	**********
Full name of joint inventor(s):		·
Inventor's signature:	Date:	:
Residence:		
Citizenship:		
Post Office Address:		:
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Full name of joint inventor(s):		:i
Inventor's signature:	Date:	· :
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